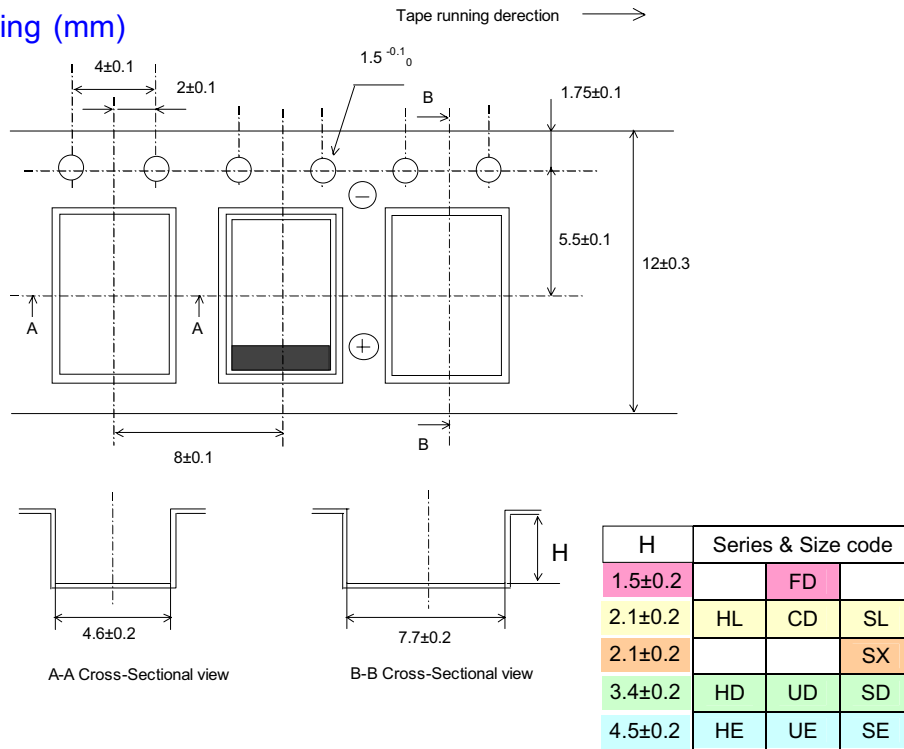


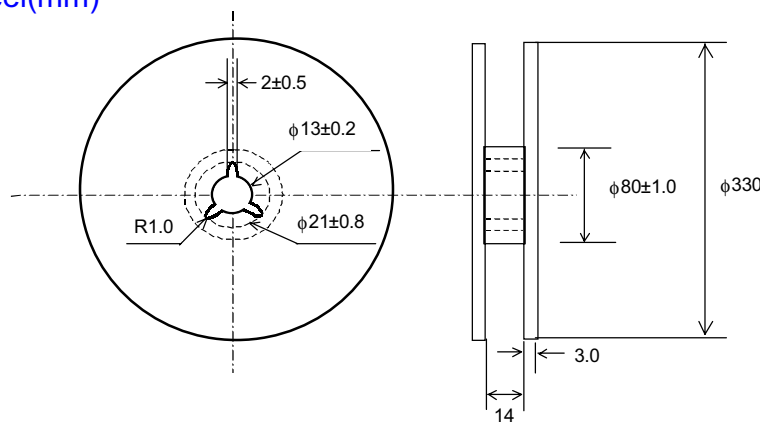


## Packaging Specifications

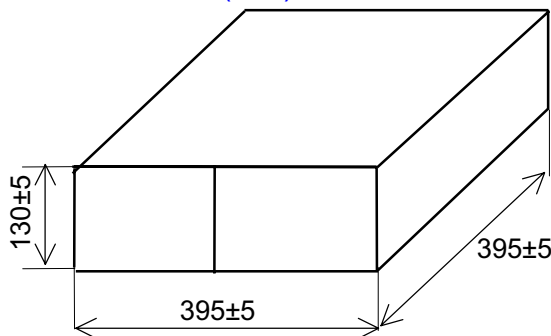
### ● Emboss taping (mm)



### ● Taping reel (mm)



### ● Packaging Box Dimensions (mm)



Packaging Specifications 19



## Soldering Specifications

We recommend soldering be done according to the following maximum permissible reflow soldering temperature profile.

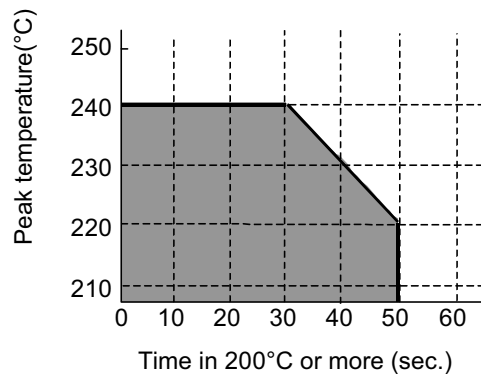
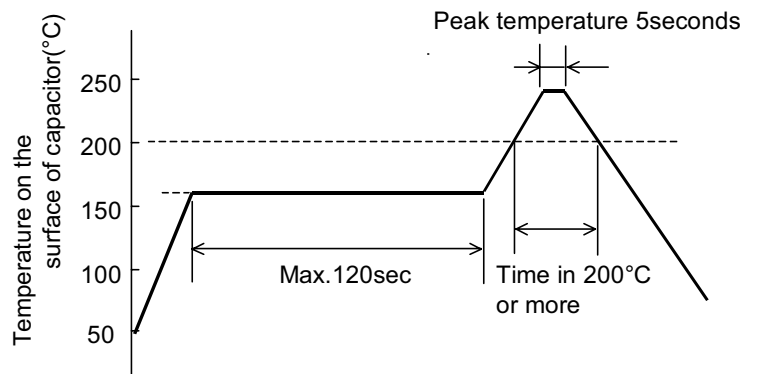
### Reflow soldering

(This is a method to heat parts and the substrate by hot air or infrared furnace.)

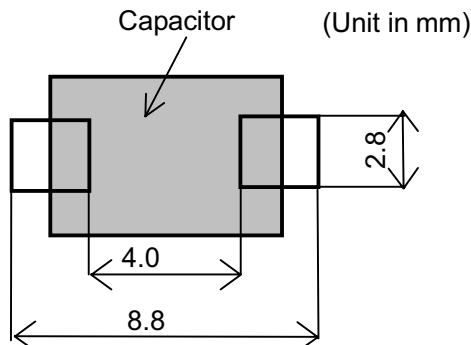
\*Do not perform reflow soldering more than twice

Please be sure to perform the second reflow soldering within 5days.

(Please refer to item 5 of the Application Guidelines for the proper storing conditions prior to the second reflow)



## Reference Land-pattern



Same land pattern design as a Tantalum electrolytic capacitor 7.3 x 4.3 mm product